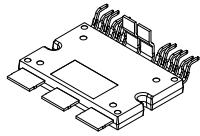


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

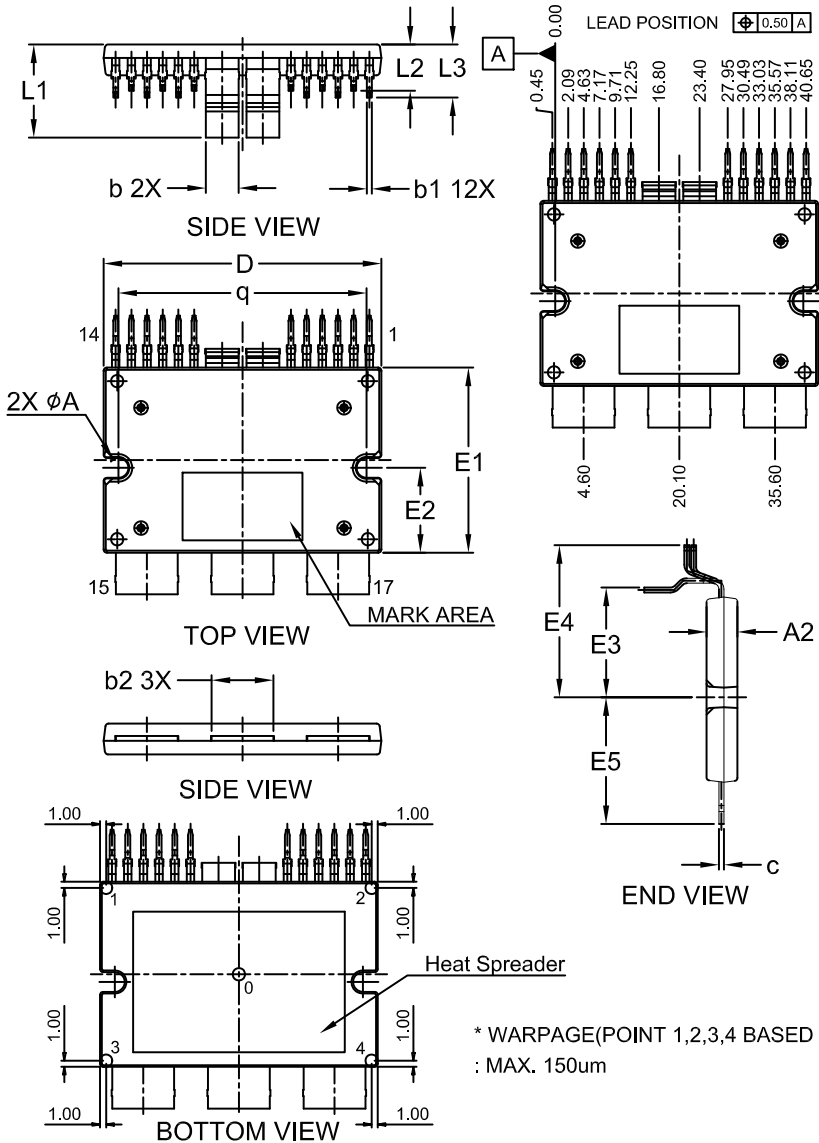


APM17-MDA AUTOMOTIVE MODULE CASE MODHU ISSUE C

DATE 07 DEC 2021

NOTES:

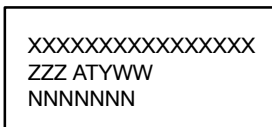
1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A2	4.90	5.00	5.10
b	5.20	5.30	5.40
b1	0.70	0.80	0.90
b2	9.90	10.00	10.10
c	0.75	0.80	0.90
D	44.90	45.00	45.10
E1	29.90	30.00	30.10
E2	13.65	13.75	13.85
E3	17.50	17.80	18.10
E4	24.35	24.65	24.95
E5	20.20	20.50	20.80
L1	14.80	15.10	15.40
L2	7.20	7.50	7.80
L3	8.30	8.60	8.90
q	40.10	40.20	40.30
ϕA	3.10	3.20	3.30

* WARPAGE (POINT 1,2,3,4 BASED ON 0)
: MAX. 150um

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
 ZZZ = Lot ID
 AT = Assembly & Test Location
 Y = Year
 WW = Work Week
 NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	APM17-MDA AUTOMOTIVE MODULE	PAGE 1 OF 1

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